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2015年3月

## FDMS86550ET60

# N 沟道 PowerTrench $^{\otimes}$ MOSFET 60 V, 245 A, 1.65 m $\Omega$

## 特性

- 扩展额定 T<sub>J</sub> 至 175°C
- 最大  $r_{DS(on)}$  = 1.65 m $\Omega$  ( $V_{GS}$  = 10 V,  $I_D$  = 32 A)
- 最大  $r_{DS(on)}$  = 2.2  $m\Omega$  ( $V_{GS}$  = 8 V,  $I_D$  = 27 A)
- r<sub>DS(on)</sub> 和高效的先进硅封装
- MSL1 耐用封装设计
- 100% 经过 UIL 测试
- 符合 RoHS 标准

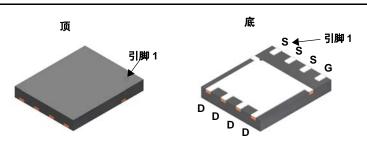


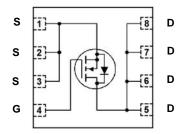
## 概述

此 N 沟道 MOSFET 采用 Fairchild 先进的 Power Trench® 工艺 生产,这一先进工艺是专为最大限度地降低导通电阻并保持卓越 开关性能而定制的。

## 应用

- 初级端 DC-DC MOSFET
- 次级端同步整流器
- 负载开关





Power 56

## MOSFET 最大额定值 T<sub>A</sub> = 25 ℃ 除非另有说明

符号		参数		额定值	单位
$V_{DS}$	漏极一源极电压			60	٧
$V_{GS}$	栅极一源极电压			±20	V
	漏极电流 - 连续	T <sub>C</sub> = 25 °C	(注5)	245	
	- 连续	T <sub>C</sub> = 100 °C	(注5)	173	A
I <sub>D</sub>	- 连续	T <sub>A</sub> = 25 °C	(注 1a)	32	^
	- 脉冲		(注 4)	1068	
E <sub>AS</sub>	单脉冲雪崩能量		(注 3)	937	mJ
P <sub>D</sub>	功耗	$T_C = 25  ^{\circ}C$		187	W
	功耗	T <sub>A</sub> = 25 °C	(注 1a)	3.3	VV
$T_J$ , $T_{STG}$	工作和存储结温范围			-55 至 +175	°C

## 热性能

$R_{\theta JC}$	结一壳体的热阻		0.8	°C/W
$R_{\theta JA}$	结至环境热阻最大值	(注 1a)	45	C/VV

### 封装标识与定购信息

器件标识	器件	封装	卷尺寸	带宽	数量
FDMS86550ET	FDMS86550ET60	Power 56	13 "	12 mm	3000 个

## 电气特性 T<sub>J</sub> = 25℃,除非另有说明

符号	参数	测试条件	最小值	典型值	最大值	单位
关断特性						
$BV_DSS$	漏极一源极击穿电压	$I_D = 250 \mu\text{A},  V_{GS} = 0 \text{V}$	60			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	击穿电压温度系数	I <sub>D</sub> = 250 μA (相对 25 °C)		31		mV/°C
I <sub>DSS</sub>	零栅极电压漏极电流	V <sub>DS</sub> = 48 V, V <sub>GS</sub> = 0 V			1	μΑ
$I_{GSS}$	栅极一源极漏电流	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

#### 导通特性

$V_{GS(th)}$	栅极一源极阈值电压	$V_{GS} = V_{DS}, I_D = 250 \mu\text{A}$	2.5	3.3	4.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	栅极一源极阈值电压温度系数	I <sub>D</sub> = 250 μA (相对 25 °C)		-12		mV/°C
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 32 A		1.4	1.65	
r <sub>DS(on)</sub>	漏极至源极静态导通电阻	V <sub>GS</sub> = 8 V, I <sub>D</sub> = 27 A		1.7	2.2	mΩ
, ,		$V_{GS} = 10 \text{ V}, I_D = 32 \text{ A}, T_J = 125 ^{\circ}\text{C}$		2.2	2.6	
g <sub>FS</sub>	正向跨导	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 32 A		96		S

## 动态特性

C <sub>iss</sub>	输入电容	V 20 V V 0 V		8235		pF
C <sub>oss</sub>	输出电容	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$		2140		рF
C <sub>rss</sub>	反向传输电容	1 - 1 1/11/12		70		pF
$R_g$	栅极阻抗		0.1	0.9	2.7	Ω

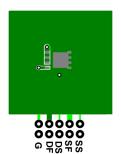
### 开关特性

t <sub>d(on)</sub>	导通延迟时间		43	69	ns
t <sub>r</sub>	上升时间	V <sub>DD</sub> = 30 V, I <sub>D</sub> = 32 A,	27	43	ns
t <sub>d(off)</sub>	关断延迟时间	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	42	67	ns
t <sub>f</sub>	下降时间		11	20	ns
$Q_g$	总栅极电荷	V <sub>GS</sub> = 0 V 到 10 V	110	154	nC
Qg	总栅极电荷	V <sub>GS</sub> = 0 V 到 8 V V <sub>DD</sub> = 30 V,	90	126	nC
Q <sub>gs</sub>	栅极一源极电荷	I <sub>D</sub> = 32 A	40		nC
$Q_{gd}$	栅极一漏极"米勒"电荷		20		nC

## 漏极 - 源极二极管特性

V	海也。	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 2.1 A (注 2)	0.7	1.2	\/
v <sub>SD</sub>	源极 - 漏极二极管正向电压	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 32 A (注 2)	8.0	1.3	V
t <sub>rr</sub>	反向恢复时间	I <sub>F</sub> = 32 A, di/dt = 100 A/μs	68	109	ns
Q <sub>rr</sub>	反向恢复电荷		62	99	nC

**注意:** 1.  $R_{\rm BJA}$  取决于安装在 FR-4 材质 1.5 x 1.5 英寸电路板上 1 英寸  $^2$  2 盎司铜焊盘上的器件。  $R_{\rm BCA}$  取决于使用者的电路板设计。



a. 45 °C/W (安装于 1 英寸 <sup>2</sup> 的 2 盎司铜焊盘。



b. 115 °C/W(安装于最小尺寸的 2 盎司铜焊盘。

- 2. 脉冲测试:脉宽 < 300 μ, 占空比 < 2.0%。
- 3. 937 mJ 的  $E_{AS}$  取决于起始  $T_J$  = 25 °C、L = 3 mH、 $I_{AS}$  = 25 A、 $V_{DD}$  = 60 V、 $V_{GS}$  = 10 V。测试百分比 100%:L = 0.1 mH、 $I_{AS}$  = 79 A。
- 4. 脉冲 ld 详情请参见图 11 SOA 曲线。
- 5. 直流理论值仅受限于最大结温,直流实际值则同时受限于热和机电电路板的设计。

## 典型特性 T」= 25 ℃ 除非另有说明

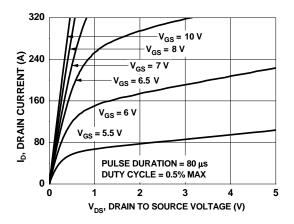


图 1. 导通区域特性

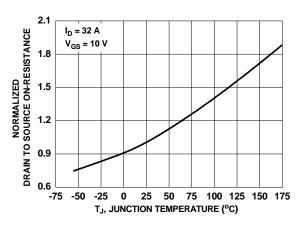


图 3. 标准化导通电阻 vs 结温

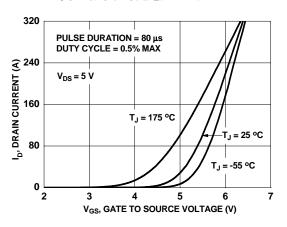


图 5. 转换特性

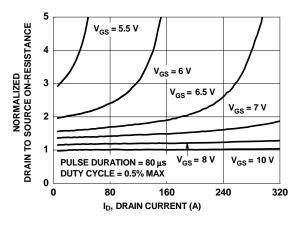


图 2. 标准化导通电阻 vs 漏极电流和栅极电压

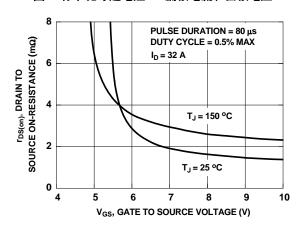


图 4. 导通电阻 vs 栅极一源极电压

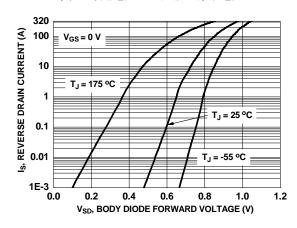


图 6. 源极一漏极二极管正向电压 vs 源极电流

## 典型特性 T」= 25 ℃ 除非另有说明

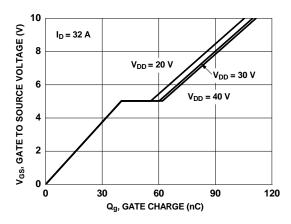


图 7. 栅极电荷特性

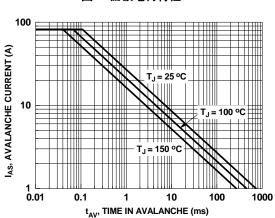


图 9. 非钳位感应开关能力

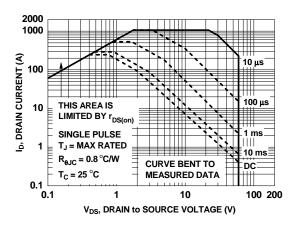


图 11. 正向偏置安全工作区

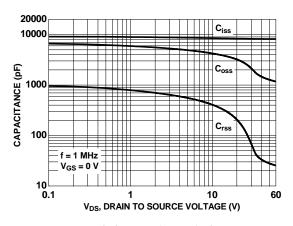


图 8. 电容 vs 漏极一源极电压

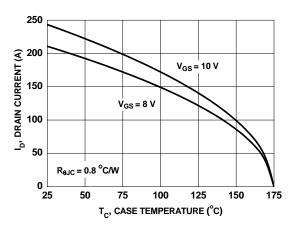


图 10. 最大连续漏极电流 vs 壳体温度

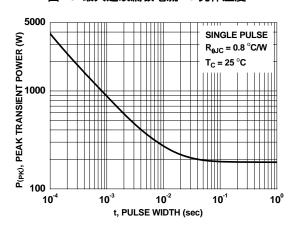


图 12. 单脉冲最大功耗

## 典型特性 T<sub>J</sub> = 25 ℃ 除非另有说明

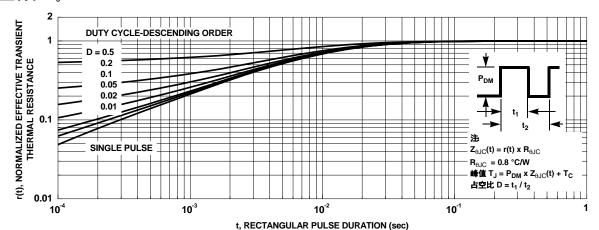
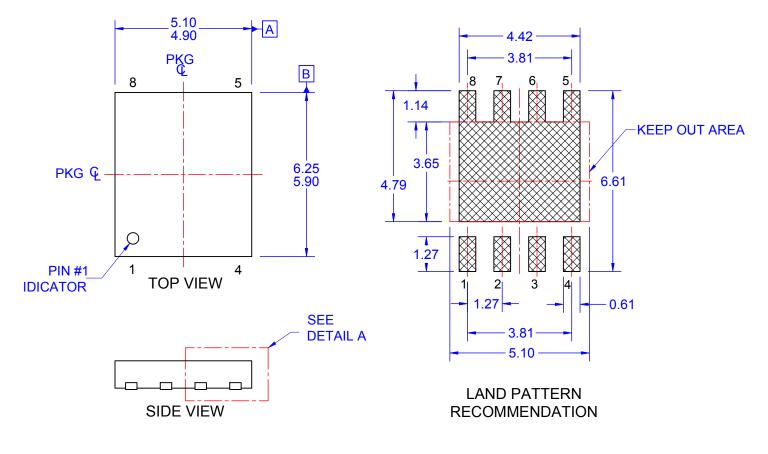
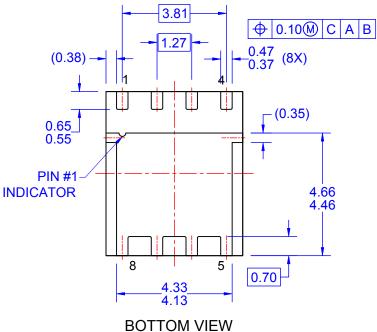
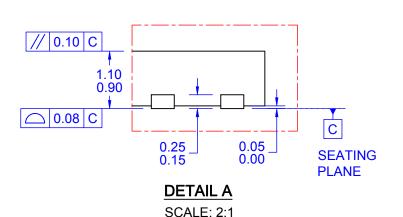


图 13. 瞬态热响应曲线







NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. AA,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
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